



Title of Change:	WLP fab site change from Gunma, Japan to Niigata, Japan
Proposed first ship date:	11 March 2016
Contact information:	Contact your local ON Semiconductor Sales Office or Hiroshi.Kojima@onsemi.com
Samples:	Contact your local ON Semiconductor Sales Office or Makoto.Nakaoka@onsemi.com
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Satoru.Fujinuma@onsemi.com
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Products manufactured at Niigata will be printed Date Code from 1547 on shipping MPN label.
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:	To continuously supply products and increase our supply capacity to support increased demand, the Wafer level package location will move from Gunma, Japan to Niigata, Japan. Most equipment and personnel was transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified.

**Reliability Data Summary:****PACKAGE :WLCSP179**

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Tj=125°C, Vcc=operating max	1008 hrs	0/77
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
THB	JESD22-A101	85°C, 85% RH, V= operating max	1008 hrs	0/77

PACKAGE :WLCSP36

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/77

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Standard Parts:

LV52130A0XA-VH
 LV52130A4XA-VH
 LV52130N0XA-VH
 LV52130N4XA-VH
 LV52207AXA-VH
 LV52207NXA-VH
 LV52207XA-VH

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If no Customer Part Number is on file, the CPN Part Number is marked “CPN Unassigned”.

MPN	CPN	Company Name	Company Code	Division Name	Division Code
LV52130A0XA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52130A4XA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52207XA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52130N0XA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52207NXA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52130N4XA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO
LV52207AXA-VH	CPN Unassigned	DIGI-KEY	DIKG	DIGI-KEY	DKCPO